SWITCHMODE Power Rectifiers

DPAK-3 Surface Mount Package

These state-of-the-art devices are designed for use in switching power supplies, inverters and as free wheeling diodes.

Features

- Extremely Fast Switching
- Extremely Low Forward Drop
- Platinum Barrier with Avalanche Guardrings
- AEC-Q101 Qualified and PPAP Capable
- NRVBD and SBR Prefixes for Automotive and Other Applications Requiring Unique Site and Control Change Requirements
- All Packages are Pb-Free*

Mechanical Characteristics:

- Case: Epoxy, Molded
- Weight: 0.4 Gram (Approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Max. for 10 Seconds
- ESD Ratings:
 - ♦ Machine Model = C
 - Human Body Model = 3B



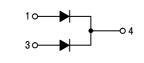
ON Semiconductor®

http://onsemi.com

SCHOTTKY BARRIER RECTIFIERS 6.0 AMPERES, 20 – 60 VOLTS



DPAK CASE 369C



MARKING DIAGRAM



Y	= Year
WW	= Work Week
B6x0T	= Device Code
х	= 2, 3, 4, 5, or 6
G	= Pb-Free Package

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 5 of this data sheet.

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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MAXIMUM RATINGS

		MBRD/NRVBD/SBR					
Rating	Symbol	620CT	630CT	640CT	650CT	660CT	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _R	20	30	40	50	60	V
Average Rectified Forward Current $T_{C} = 130^{\circ}C$ (Rated V_{R}) Per Diode Per Device	I _{F(AV)}			3 6			A
Peak Repetitive Forward Current, T _C = 130°C (Rated V _R , Square Wave, 20 kHz) Per Diode	I _{FRM}			6			A
Nonrepetitive Peak Surge Current – (Surge applied at rated load conditions halfwave, single phase, 60 Hz)	I _{FSM}	75		A			
Peak Repetitive Reverse Surge Current (2 μs, 1 kHz)	I _{RRM}	1		А			
Operating Junction Temperature (Note 1)	TJ		-	65 to +17	5		°C
Storage Temperature	T _{stg}	-65 to +175		°C			
Voltage Rate of Change (Rated V _R)	dv/dt	10,000		V/μs			

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. The heat generated must be less than the thermal conductivity from Junction-to-Ambient: $dP_D/dT_J < 1/R_{\theta JA}$.

THERMAL CHARACTERISTICS PER DIODE

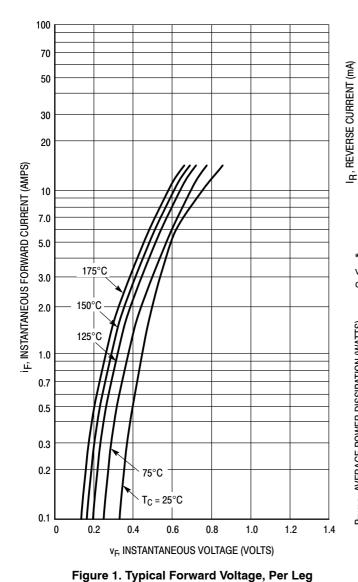
Characteristic	Symbol	Value	Unit
Maximum Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	6	°C/W
Maximum Thermal Resistance, Junction-to-Ambient (Note 2)	R_{\thetaJA}	80	°C/W

2. Rating applies when surface mounted on the minimum pad size recommended.

ELECTRICAL CHARACTERISTICS PER DIODE

Characteristic	Symbol	Value	Unit
Maximum Instantaneous Forward Voltage (Note 3) $i_F = 3 \text{ Amps}, T_C = 25^{\circ}\text{C}$ $i_F = 3 \text{ Amps}, T_C = 125^{\circ}\text{C}$ $i_F = 6 \text{ Amps}, T_C = 25^{\circ}\text{C}$ $i_F = 6 \text{ Amps}, T_C = 125^{\circ}\text{C}$	V _F	0.7 0.65 0.9 0.85	V
Maximum Instantaneous Reverse Current (Note 3) (Rated dc Voltage, $T_C = 25^{\circ}C$) (Rated dc Voltage, $T_C = 125^{\circ}C$)	i _R	0.1 15	mA

3. Pulse Test: Pulse Width = 300 μ s, Duty Cycle \leq 2.0%.



TYPICAL CHARACTERISTICS

1000 100 T_{.1} = 175°C 150°C 10 125°C 1.0 75°C 0.1 0.01 0.001 25°C 0.0001 0 10 20 30 40 50 60 70 V_R, REVERSE VOLTAGE (VOLTS)

*The curves shown are typical for the highest voltage device in the voltage grouping. Typical reverse current for lower voltage selections can be estimated from these curves if $V_{\rm R}$ is sufficient below rated $V_{\rm R}.$



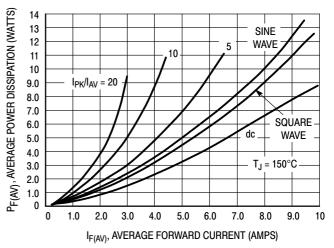
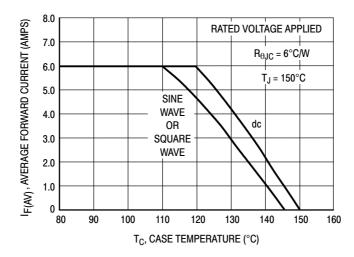
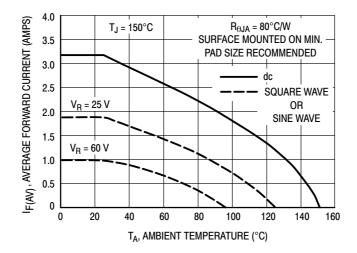


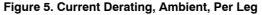
Figure 3. Average Power Dissipation, Per Leg



TYPICAL CHARACTERISTICS







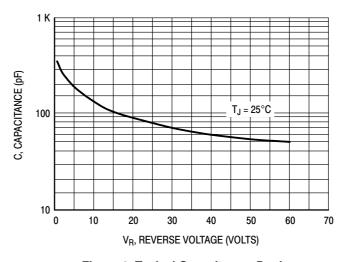


Figure 6. Typical Capacitance, Per Leg

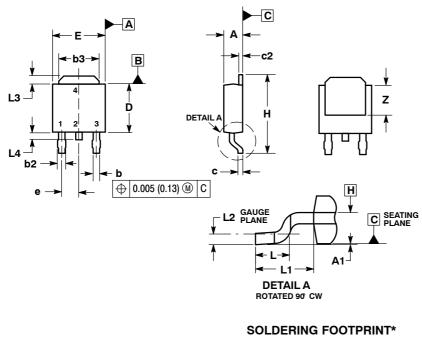
ORDERING INFORMATION

Device	Package	Shipping [†]		
MBRD620CTT4G	DPAK (Pb-Free)	2,500 Tape & Reel		
MBRD630CTT4G	DPAK (Pb-Free)	2,500 Tape & Reel		
MBRD640CTG	DPAK-3 (Pb-Free)	75 Units / Rail		
NRVBD640CTG	DPAK-3 (Pb-Free)	75 Units / Rail		
MBRD640CTT4G	DPAK-3 (Pb-Free)	2,500 Tape & Reel		
NRVBD640CTT4G	DPAK-3 (Pb-Free)	2,500 Tape & Reel		
SBR640CTT4G	DPAK-3 (Pb-Free)	2,500 Tape & Reel		
MBRD650CTG	DPAK (Pb-Free)	75 Units / Rail		
MBRD650CTT4G	DPAK (Pb-Free)	2,500 Tape & Reel		
NRVBD650CTT4G	DPAK (Pb-Free)	2,500 Tape & Reel		
MBRD660CTG	DPAK-3 (Pb-Free)	75 Units / Rail		
NRVBD660CTG	DPAK-3 (Pb-Free)	75 Units / Rail		
MBRD660CTRLG	DPAK-3 (Pb-Free)	1,800 Tape & Reel		
MBRD660CTT4G	DPAK-3 (Pb-Free)	2,500 Tape & Reel		
NRVBD660CTT4G	DPAK-3 (Pb-Free)	2,500 Tape & Reel		
SBR660CTT4G	DPAK-3 (Pb-Free)	2,500 Tape & Reel		

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

PACKAGE DIMENSIONS

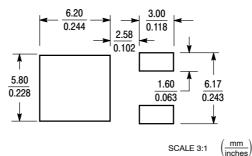
DPAK (SINGLE GAUGE) CASE 369C-01 ISSUE D



NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ASME
- Y14.5M, 1994. 2. CONTROLLING DIMENSION: INCHES. 3. THERMAL PAD CONTOUR OPTIONAL WITHIN DI-
- MENSIONS b3, L3 and Z. 4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.006 INCHES PER SIDE.
- DIMENSIONS D AND E ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY.
 DATUMS A AND B ARE DETERMINED AT DATUM
- PLANE H.

	INC	HES	MILLIM	ETERS	
DIM	MIN	MAX	MIN	MAX	
Α	0.086	0.094	2.18	2.38	
A1	0.000	0.005	0.00	0.13	
b	0.025	0.035	0.63	0.89	
b2	0.030	0.045	0.76	1.14	
b3	0.180	0.215	4.57	5.46	
С	0.018	0.024	0.46	0.61	
c2	0.018	0.024	0.46	0.61	
D	0.235	0.245	5.97	6.22	
E	0.250	0.265	6.35	6.73	
е	0.090 BSC		2.29 BSC		
н	0.370	0.410	9.40	10.41	
L	0.055	0.070	1.40	1.78	
L1	0.108 REF		2.74	2.74 REF	
L2	0.020 BSC		0.51).51 BSC	
L3	0.035	0.050	0.89	1.27	
L4		0.040		1.01	
Z	0.155		3.93		



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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